



# ACE4710B

## P-Channel Enhancement Mode MOSFET with Schottky Diode

### Description

ACE4710B combines a P-Channel enhancement mode power MOSFET which is produced with high cell density and DMOS trench technology and a low forward voltage schottky diode. This device particularly suits low voltage applications, especially for battery powered circuits, the tiny and thin outline saves PCB consumption.

### Features

#### MOSFET

- $V_{DS}(V)=-20V$
- $I_D=-4A$
- $R_{DS(ON)}@-4.5V, 58m\Omega$  (Typ.)
- $R_{DS(ON)}@-2.5V, 76m\Omega$  (Typ.)
- $R_{DS(ON)}@-1.8V, 97m\Omega$  (Typ.)

#### Schottky

- VR 20V
- IF 2A
- $V_F@1A<430mV$

### Application

- Li Battery Charging
- High Side DC/DC Converter
- High Side Driver for Brushless DC Motor
- Power Management in Portable, Battery Powered Devices

### Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Drain-Source Voltage	$V_{DSS}$	-20	V
Gate-Source Voltage	$V_{GSS}$	$\pm 8$	V
Drain Current (Continuous)	Continuous	-4	A
	Pulsed	-25	
Schottky Reverse Voltage	$V_R$	20	V
Schottky Continuous Forward Current	$I_F$	2	A
Power Dissipation Derating above $T_A=25^\circ C$ (Note 1)	$P_D$	1.5	W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

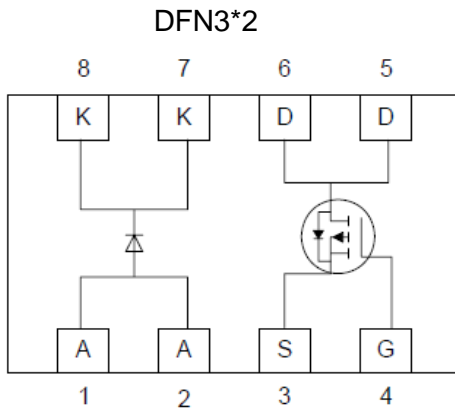
Note: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inches. The rating is for each chip in the package.



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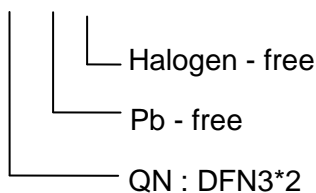
## P-Channel Enhancement Mode MOSFET with Schottky Diode

### Packaging Type



### Ordering information

ACE4710B XX + H



### Electrical Characteristics

$T_A=25\text{ }^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
P-channel Enhancement Mode MOSFET						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V$			-1	$\mu A$
Gate Leakage Current	$I_{GSS}$	$V_{GS}=\pm 8V, V_{DS}=0V$			$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-4A$		58	96	m $\Omega$
		$V_{GS}=-2.5V, I_D=-3A$		76	118	
		$V_{GS}=-1.8V, I_D=-2A$		97	236	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-0.5	-0.7	-1.2	V
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=-6V, R_L=6\Omega,$ $R_G=6\Omega, V_{GEN}=-4.5V,$ $I_D=-1A$		20		ns
Turn-On Rise Time	$t_r$			18		
Turn-Off Delay Time	$t_{d(off)}$			300		
Turn-Off Fall Time	$t_f$			120		
Input Capacitance	$C_{iss}$	$V_{DS}=-6V, V_{GS}=0V$ $f=1MHz$		450		pF
Output Capacitance	$C_{oss}$			180		
Reverse Transfer Capacitance	$C_{rss}$			90		



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Schottky Diode						
Breakdown Voltage	$V_R$	$I_R=300\mu A$	20			V
Forward Voltage Drop	$V_F$	$I_F=1A$		0.37	0.43	V
Maximum reverse leakage current	$I_R$	$V_R=20V$		15	200	$\mu A$

Note : 2. Short duration test pulse used to minimize self-heating effect.

### Typical Performance Characteristics

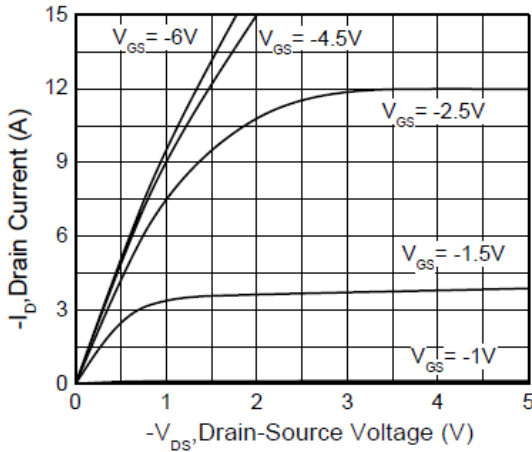


Figure 1. Output Characteristics

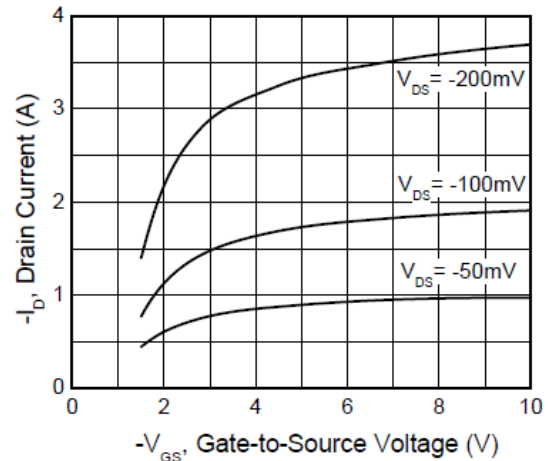


Figure 2. Transfer Characteristics

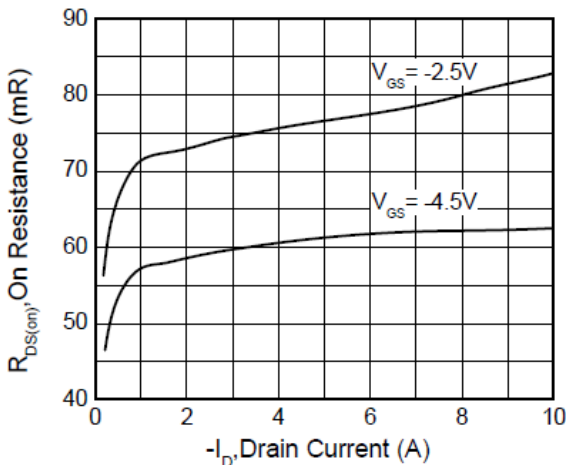


Figure 3. On Resistance Vs. Drain Current

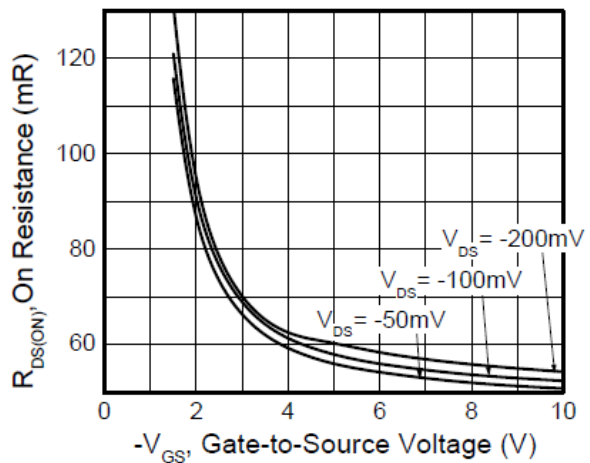


Figure 4. On Resistance Vs. Gate-Source Voltage



Typical Performance Characteristics

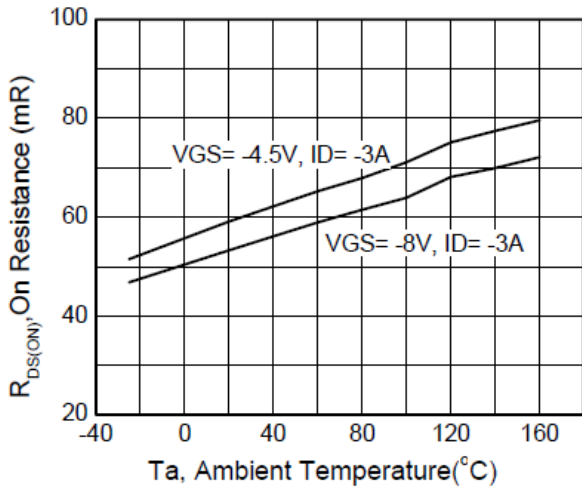


Figure 5. On Resistance Vs. Temperature

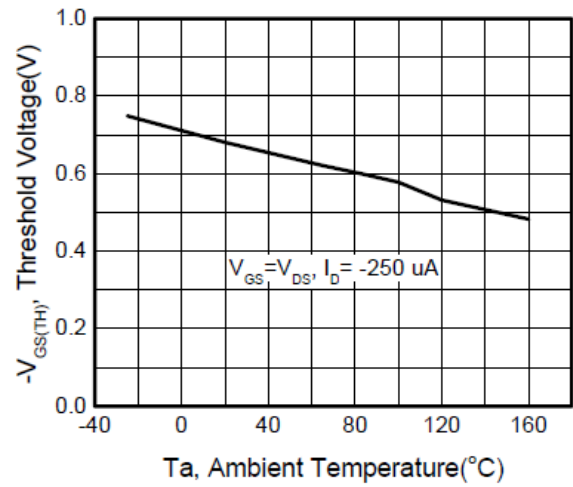


Figure 6. Threshold Voltage Vs. Temperature

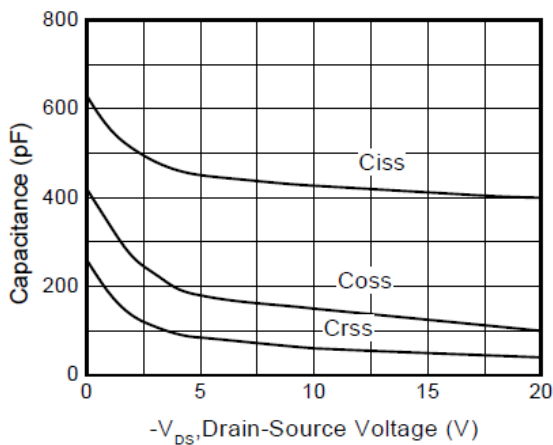


Figure 8. Capacitance

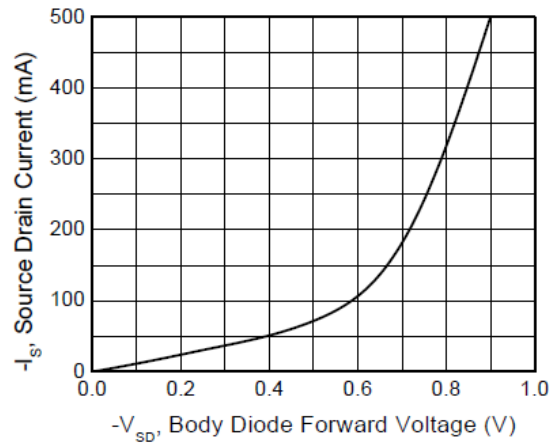


Figure 7. Body Diode Forward Characteristics

● Schottky Diode Typical Performance Characteristics

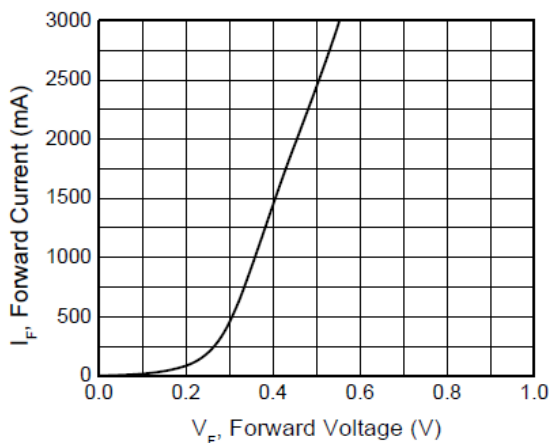


Figure 9. Schottky Forward Characteristics

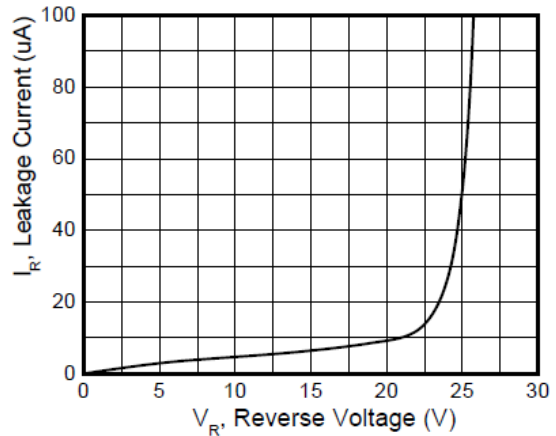
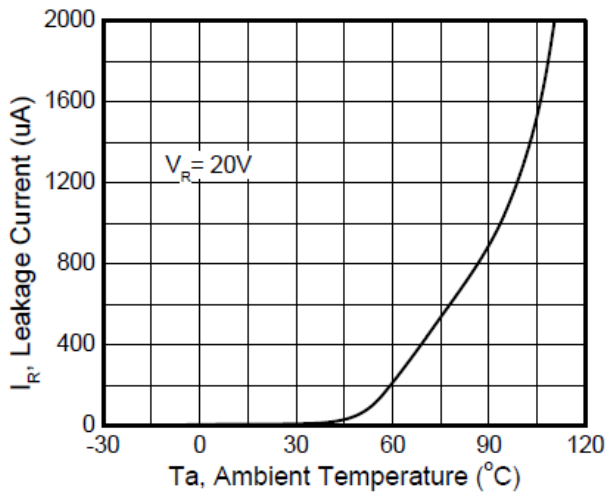


Figure 10. Schottky Reverse Characteristics



**Typical Performance Characteristics**



**Figure 11. Leakage Current Vs. Temperature**

**Packing Information**

**DFN3\*2**

Package:DFN3X2			
Unit:mm			
Dim	Min	Typ	Max
A	0.70	0.80	0.90
A1	0.00	---	0.05
c	0.08	0.152	0.25
D	3.00 BSC		
E	2.00 BSC		
E1	1.70 BSC		
e	0.65 BSC		
L	0.20	0.275	0.40

Unit: mm



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### Notes

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As sued herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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